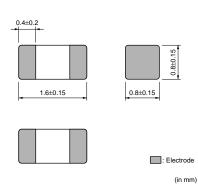
Data Sheet

EMIFIL[®] (Inductor type) Chip Ferrite Bead BLM18P Series (0603 Size)

Dimensions



Equivalent Circuit

1

(Resistance element becomes dominant at high frequencies.)

Packaging

Code	Packaging	Minimum Quantity	
D	180mm Paper Tape	4000	
J	330mm Paper Tape	10000	
В	Bulk(Bag)	1000	

■ Rated Value (□: packaging code)

Part Number	Impedance (at 100MHz/20°C)	Impedance (at 1GHz/20°C)	Rated Current	DC Resistance	Operating Temperature Range
BLM18PG300SN1	30ohm(Typ.)	-	1000mA	0.05ohm max	-55 to +125°C
BLM18PG330SN1	33ohm±25%	-	3000mA	0.025ohm max	-55 to +125°C
BLM18PG600SN1	60ohm(Typ.)	-	500mA	0.10ohm max	-55 to +125°C
BLM18PG121SN1	120ohm±25%	-	2000mA	0.05ohm max	-55 to +125°C
BLM18PG181SN1	180ohm±25%	-	1500mA	0.09ohm max	-55 to +125°C
BLM18PG221SN1	220ohm±25%	-	1400mA	0.10ohm max	-55 to +125°C
BLM18PG331SN1	330ohm±25%	-	1200mA	0.15ohm max	-55 to +125°C
BLM18PG471SN1	470ohm±25%	-	1000mA	0.20ohm max	-55 to +125°C

Number of Circuits: 1

Continued on the following page.

• This data sheet is applied for CHIP FERRITE BEAD used for General Electronics equipment for your design.

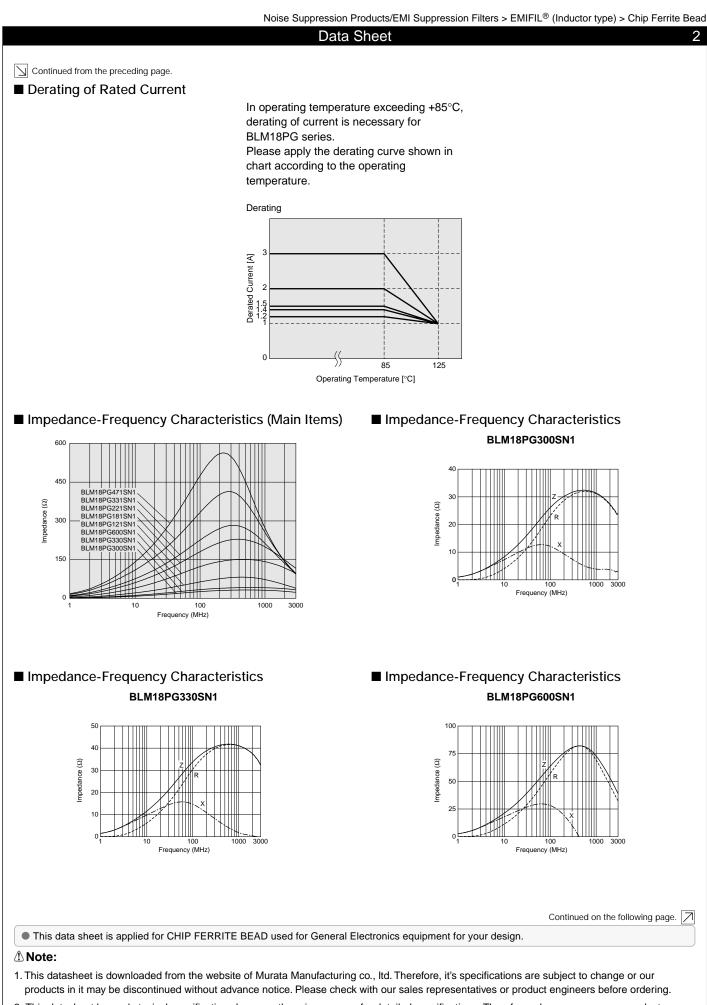
A Note:

1. This datasheet is downloaded from the website of Murata Manufacturing co., ltd. Therefore, it's specifications are subject to change or our products in it may be discontinued without advance notice. Please check with our sales representatives or product engineers before ordering.

2. This datasheet has only typical specifications because there is no space for detailed specifications. Therefore, please approve our product specifications or transact the approval sheet for product specifications before ordering.



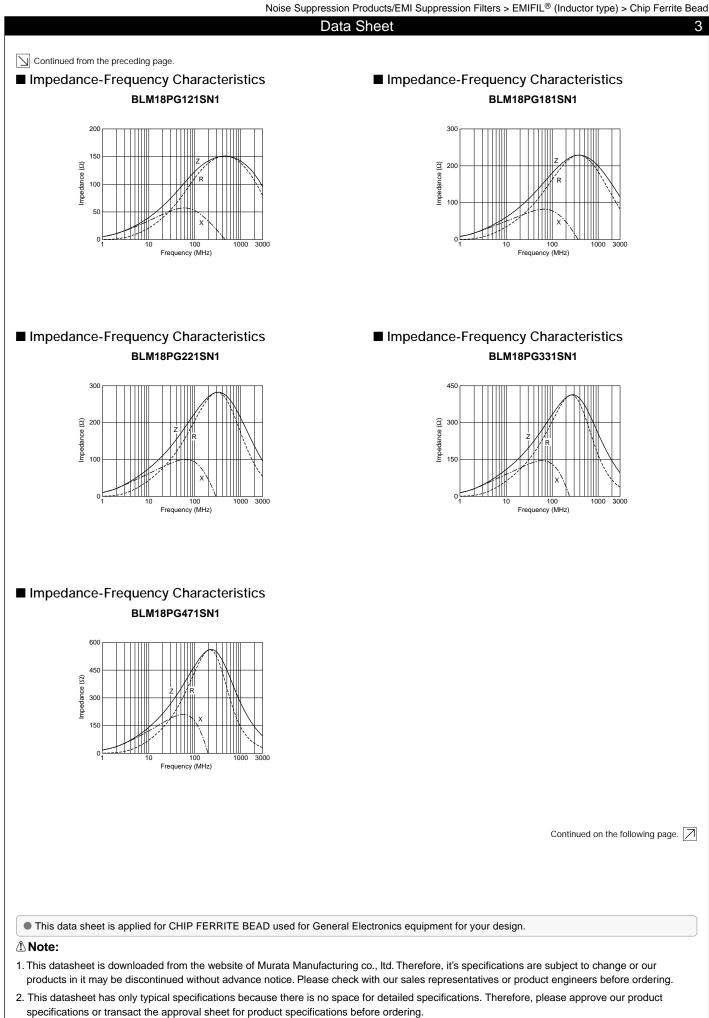




2. This datasheet has only typical specifications because there is no space for detailed specifications. Therefore, please approve our product specifications or transact the approval sheet for product specifications before ordering.









Data Sheet

Continued from the preceding page.

■ ①Caution/Notice

Do not use products beyond the rated current as this may create excessive heat and deteriorate the insulation resistance.

Notice

Solderability of Tin plating termination chip might be deteriorated when low temperature soldering profile where peak solder temperature is below the Tin melting point is used. Please confirm the solderability of Tin plating termination chip before use. 4

• This data sheet is applied for CHIP FERRITE BEAD used for General Electronics equipment for your design.

A Note:

1. This datasheet is downloaded from the website of Murata Manufacturing co., ltd. Therefore, it's specifications are subject to change or our products in it may be discontinued without advance notice. Please check with our sales representatives or product engineers before ordering.

2. This datasheet has only typical specifications because there is no space for detailed specifications. Therefore, please approve our product specifications or transact the approval sheet for product specifications before ordering.

